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 Members of the Texas Instruments Widebus[™] Family 	SN54ABT162500 WD PACKAGE SN74ABT162500 DL PACKAGE (TOP VIEW)
 B-Port Outputs Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required 	$\begin{array}{c} (101 \text{ VLM}) \\ \text{OEAB} \begin{bmatrix} 1 & 56 \end{bmatrix} \text{GND} \\ \text{LEAB} \begin{bmatrix} 2 & 55 \end{bmatrix} \text{CLKAB} \end{array}$
 State-of-the-Art EPIC-IIB[™] BiCMOS Design Significantly Reduces Power Dissipation 	A1 [] 3 54]] B1 GND [] 4 53]] GND
 UBT[™] (Universal Bus Transceiver) Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, 	$\begin{array}{cccc} A2 \begin{bmatrix} 5 & 52 \end{bmatrix} B2 \\ A3 \begin{bmatrix} 6 & 51 \end{bmatrix} B3 \\ V_{CC} \begin{bmatrix} 7 & 50 \end{bmatrix} V_{CC} \end{array}$
 Latched, or Clocked Mode Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C 	A4 [] 8 49 [] B4 A5 [] 9 48] B5 A6 [] 10 47] B6
 High-Impedance State During Power Up and Power Down 	GND 11 46 GND A7 12 45 B7
 Flow-Through Architecture Optimizes PCB Layout 	A8 13 44 B8 A9 14 43 B9 A10 15 42 B10
 Latch-Up Performance Exceeds 500 mA Per JESD 17 	A11 [] 16 41]] B11 A12 [] 17 40 [] B12
 ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0) 	GND 18 39 GND A13 19 38 B13 A14 20 37 B14
 Package Options Include Plastic Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package 	A15
Using 25-mil Center-to-Center Spacings	A17 [] 24 33 [] B17 GND [] 25 32 [] GND

description

These 18-bit universal bus transceivers combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, and clocked modes. Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs.

For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the high-to-low transition of CLKAB. Output-enable OEAB is active high. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state.

A18

27

28

OEBA

LEBA [

31

29

B18 30 CLKBA

GND

Data flow for B to A is similar to that of A to B but uses OEBA, LEBA, and CLKBA. The output enables are complementary (OEAB is active high and OEBA is active low).

The B-port outputs, which are designed to source or sink up to 12 mA, include equivalent 25Ω series resistors to reduce overshoot and undershoot.



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description (continued)

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, OE should be tied to V_{CC} through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

The SN54ABT162500 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT162500 is characterized for operation from -40°C to 85°C.

	INPUTS								
OEAB	LEAB	CLKAB	Α	В					
L	Х	Х	Х	Z					
н	Н	Х	L	L					
н	Н	Х	Н	н					
н	L	\downarrow	L	L					
н	L	\downarrow	Н	н					
н	L	Н	Х	в ₀ ‡ в ₀ §					
н	L	L	Х	в ₀ §					
±									

FUNCTION TABLE[†]

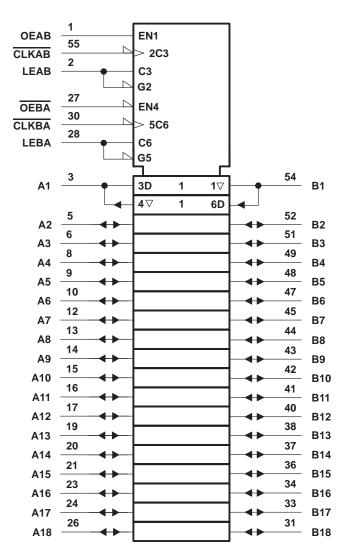
[†]A-to-B data flow is shown: B-to-A flow is similar but uses OEBA, LEBA, and CLKBA.

[‡]Output level before the indicated steady-state input conditions were established

§ Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low



logic symbol[†]

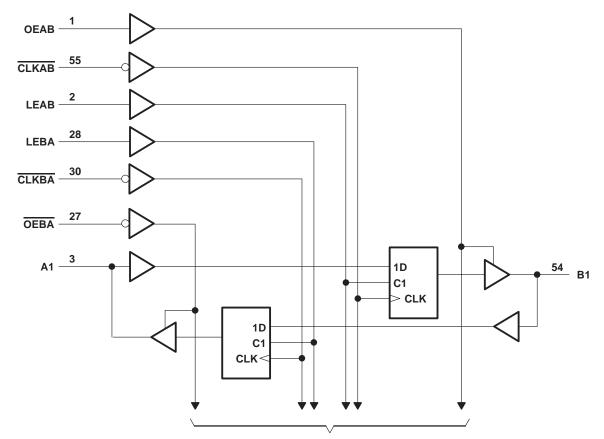


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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logic diagram (positive logic)



To 17 Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, Vo	–0.5 V to 5.5 V
Current into any output in the low state, I _O : SN54ABT162500 (A port)	96 mA
SN74ABT162500 (A port)	128 mA
B port	30 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I_{OK} (V _O < 0)	
Package thermal impedance, θ_{JA} (see Note 2): DL package	
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51.



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recommended operating conditions (see Note 3)

			SN54ABT	162500	SN74ABT	162500	UNIT
			MIN	MAX	MIN	MAX	UNIT
V _{CC}	Supply voltage	4.5	5.5	4.5	5.5	V	
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage		0	Vcc	0	VCC	V
	High-level output current	A port		-24		-32	mA
ЮН	nigh-level output current	B port	1	-12		-12	IIIA
le.		A port	206	48		64	mA
IOL	Low-level output current	B port	20	12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled	Q	10		10	ns/V
$\Delta t / \Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DAMETED	TERT		Т	A = 25°C		SN54ABT	162500	SN74ABT	162500	UNIT	
PA	RAMETER	TEST COI	NDITIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK		$V_{CC} = 4.5 V$, $I_{I} = -18 mA$				-1.2		-1.2		-1.2	V	
		V _{CC} = 4.5 V,	I _{OH} = -3 mA	2.5			2.5		2.5			
	A mant	V _{CC} = 5 V,	I _{OH} = -3 mA	3			3		3			
	A port	V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2					
Vari			I _{OH} = -32 mA	2*					2		V	
Vон		V _{CC} = 4.5 V,	I _{OH} = -1 mA	3.35			3.3		3.35		v	
	B port	$V_{CC} = 5 V,$	I _{OH} = -1 mA	3.85			3.8		3.85			
	B port		I _{OH} = -3 mA	3.1			3		3.1			
		V _{CC} = 4.5 V	I _{OH} = -12 mA	2.6					2.6			
	Aport	V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55				
VOL	A port	VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V	
	B port	V _{CC} = 4.5 V,	I _{OL} = 12 mA			0.8		0.8		0.8		
V _{hys}					100						mV	
	Control inputs	$V_{CC} = 0$ to 5.5 V, V	$V_{I} = V_{CC} \text{ or } GND$			±1		<u></u>		±1		
I	A or B ports	$V_{CC} = 2.1 V \text{ to } 5.5$ $V_{I} = V_{CC} \text{ or GND}$	V,			±20		±20		±20	μA	
IOZPU	J	$V_{CC} = 0 \text{ to } 2.1 \text{ V},$ $V_{O} = 0.5 \text{ V to } 2.7 \text{ V}$	$V_{CC} = 0 \text{ to } 2.1 \text{ V},$ $V_O = 0.5 \text{ V to } 2.7 \text{ V}, \overline{\text{OE}} \text{ or } \text{OE} = X\$$			±50	UCY	±50		±50	μA	
IOZPE)	$V_{CC} = 2.1 V \text{ to } 0,$ $V_{O} = 0.5 V \text{ to } 2.7 V$	\sqrt{OE} or $OE = X$			±50	PRO1	±50		±50	μA	
^I OZH [‡]	ŧ	$V_{CC} = 2.1 \text{ V to } 5.5$ $V_{O} = 2.7 \text{ V}, \text{ OE} \ge 2$	V, V or OE ≤ 0.8 V			10		10		10	μA	
IOZL‡	:	$V_{CC} = 2.1 \text{ V to } 5.5$ $V_{O} = 0.5 \text{ V}, \text{ OE} \ge 2$	V, V or OE ≤ 0.8 V			-10		-10		-10	μA	
loff		V _{CC} = 0,	$V_I \text{ or } V_O \leq 4.5 \text{ V}$			±100				±100	μA	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ	
	A port			-50	-110	-180	-50	-180	-50	-180		
IO¶	B port	V _{CC} = 5.5 V,	V _O = 2.5 V	-25	-55	-90	-25	-90	-25	-90	mA	
		V _{CC} = 5.5 V,	Outputs high			3		3		3		
ICC	A or B ports	$I_{O} = 0,$	Outputs low			36		36		36	mA	
		$V_{I} = V_{CC}$ or GND	Outputs disabled			3		3		3		
∆l _{CC} ‡	ŧ		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND			50		50		50	μA	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			3						pF	
C _{io}	A or B ports	$V_{O} = 2.5 \text{ V or } 0.5 \text{ V}$			9						pF	

* On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 V$.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

§ For V_{CC} between 2.1 V and 4 V, OE should be less than or equal to 0.5 V to ensure a low state.

¶Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[#]This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

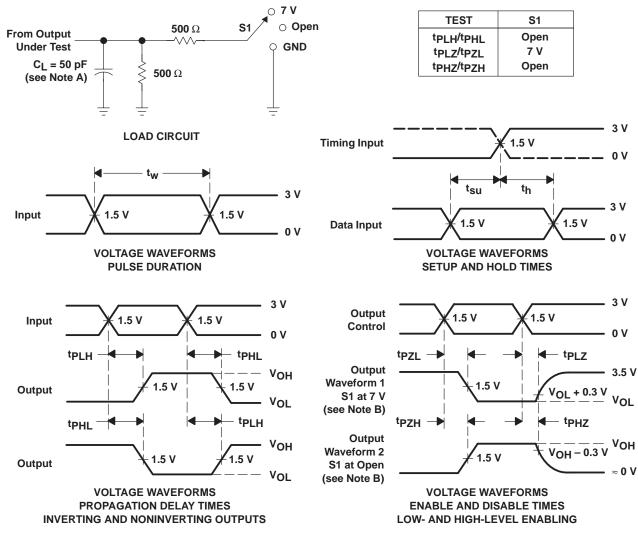
				SN54ABT	162500	SN74ABT	162500	UNIT
				MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency				150		150	MHz
tw. Pulse duration		LEAB or LEBA high		2.5	h	2.5		20
tw	Fuise duration	CLKAB or CLKBA high or low	3	VIE	3		ns	
	A before CLKAB↓			3.3	J.L.	3.3		
	Cotup time	B before CLKBA↓	3.3	ζ	3.3		ns	
t _{su}	Setup time	Setup time A before LEAB↓ or B before LEBA↓	CLK high	5		1		ns
		A before LEAB to before LEBA	CLK low	2.5		2.5		
÷.	Hold time	A after $\overline{\text{CLKAB}}\downarrow$ or B after $\overline{\text{CLKBA}}\downarrow$	after CLKAB↓ or B after CLKBA↓			0		20
th		A after LEAB \downarrow or B after LEBA \downarrow	A after LEAB \downarrow or B after LEBA \downarrow			2		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)		TO $V_{CC} = 5 V,$ (OUTPUT) $T_A = 25^{\circ}C$			SN54ABT	162500	SN74ABT	UNIT	
		(001101)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			150	200		150		150		MHz
^t PLH	A or B	B or A	1.5	2.6	4	1.5	5.1	1.5	4.8	ns
^t PHL	AUB	B of A	2	3.4	5.2	2	6.1	2	5.7	115
^t PLH	LEAB or LEBA	B or A	2	3.3	4.8	2	6.1	2	5.6	ns
^t PHL	LEAD OF LEDA	BOLA	2	3.8	5.2	2 0	6.4	2	5.9	115
^t PLH		B or A	1.5	3.7	4.9	1.5	6.4	1.5	5.9	ns
^t PHL	CLKAB or CLKBA	BUIA	1.5	3.8	5.2	1.5	6.4	1.5	6	115
^t PZH		B or A	1.5	3.4	4.6	x 1.5	5.6	1.5	5.3	ns
^t PZL	OEAB or OEBA	BUIA	2	3.8	4.7	2	5.6	2	5.4	115
^t PHZ		B or A	2	4.5	5.7	2	6.9	2	6.5	ns
^t PLZ	OEAB or OEBA	BUTA	1.5	3.8	5.3	1.5	6.3	1.5	5.8	115



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ABT162500DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT162500DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT162500DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT162500DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are noming	nal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT162500DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1



PACKAGE MATERIALS INFORMATION

11-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT162500DLR	SSOP	DL	56	1000	346.0	346.0	49.0

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